

Title (en)
Semiconductor device and method of forming

Title (de)
Halbleiteranordnung und Herstellungsverfahren

Title (fr)
Dispositif semi-conducteur et procédé de fabrication

Publication
EP 0690497 A3 19970611 (EN)

Application
EP 95109712 A 19950622

Priority
US 26924194 A 19940630

Abstract (en)
[origin: US5467253A] A semiconductor device having a substrate support (22) and a method of forming the semiconductor device. A substrate (11) has conductive traces (12) and a bonding pad (13) on a bottom surface and conductive traces (14) and a semiconductor chip attach pad (17) on a top surface. The substrate support (22) has an aperture (23) and is coupled to the substrate (11). A semiconductor chip (31) is coupled to the semiconductor chip attach pad (17). The semiconductor chip (31) is covered by an encapsulating material (38) or a cap (41, 51) which provide protection for the semiconductor chip (31).

IPC 1-7
H01L 23/24; **H01L 23/42**; **H01L 23/04**

IPC 8 full level
H01L 23/04 (2006.01); **H01L 23/057** (2006.01); **H01L 23/12** (2006.01); **H01L 23/31** (2006.01); **H01L 23/498** (2006.01)

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Citation (search report)
• [Y] EP 0582052 A1 19940209 - MOTOROLA INC [US]
• [XY] PATENT ABSTRACTS OF JAPAN vol. 018, no. 066 (E - 1501) 3 February 1994 (1994-02-03)
• [Y] PATENT ABSTRACTS OF JAPAN vol. 014, no. 489 (E - 0994) 24 October 1990 (1990-10-24)
• [Y] PATENT ABSTRACTS OF JAPAN vol. 012, no. 044 (E - 581) 9 February 1988 (1988-02-09)

Designated contracting state (EPC)
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